

C1812X182MATAC7210

SMD Comm X8G HT150C Flex, Ceramic, 1,800 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

	Specifications	
	Capacitance	1,800 pF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	20%
	Voltage DC	250 VDC
	Dielectric Withstanding Voltage	625 VDC
	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
e	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

Dimensions 1812 Chip Size 4.5mm +/-0.4mm

Click here for the 3D model.

W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

Packaging Specifications

L

Packaging T&R,	330mm, Plastic Tape
Packaging Quantity 4000	

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